EMBEDDED INSIDERS PODCAST

More Free Money & What NVIDIA Didn't Buy

In part 2 of the Embedded Insiders' analysis of recent industry acquisitions, Stacey Higginbotham, a tech industry expert and editor of the eponymous Stacey on IoT blog, joins Brandon and Rich to further the discussion about the ARM/NVIDIA deal. Wait. What did NVIDIA buy? Or better yet, what didn’t they buy? Why didn’t they acquire the entire Arm portfolio? And where is the rest of it now?

After, Jim McGregor of Tirias Research returns to analyze AMD's acquisition of programmable logic supplier Xilinx.

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Wireless Connectivity News

Silicon Labs Expands Wireless Module Portfolio with Four New Modules

Silicon Labs has expanded its portfolio of pre-certified wireless modules for IoT application development. The expansion is compiled of four new modules including the xGM210PB, BGM220, MGM220, and BGX220 Xpress.

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IoT: Implications on Database Management

Data management - from embedded to IoT systems. Learn about new database management requirements to meet these new challenges.

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Analog Market News

Semico Releases New Report on Analog Market


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AI EDGE PROCESSING NEWS

Samsung and VeriSilicon Enable Blaize to Meet Time-to-Market Goals for New AI Edge Processor

Samsung Electronics, in collaboration with design services provider, VeriSilicon, has supported the on-time market launch of AI Edge computing startup Blaize's hardware platform.

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IoT Development Kit Guide

Help for embedded and Internet of Things (IoT) design engineers to efficiently identify evaluation kits for system prototyping.

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Embedded Toolbox: The Ins and Outs of IP Protection for Embedded Systems

According to analysts, IP theft costs industry a staggering $500 to $600 billion per year. With more than half a trillion dollars at stake, you’d think that IP protection would be top of mind for many electronic device manufacturers.

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EMBEDDED EXECUTIVE PODCAST

Dr. Phil Lessner, SVP/CTO, KEMET

Higher voltages and higher frequencies are becoming commonplace in embedded designs. That in itself doesn’t necessarily cause an issue. But, when you add in that packages continue to shrink in size, you have the potential for detrimental heat and airflow issues. How do you deal with that?
That's where the discussion started with Dr. Phil Lessner, the Senior Vice President and Chief Technology Officer, at KEMET. He had lots of advice for system designers in this week's Embedded Executives podcast.

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